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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE: NEW ASSIGNMENT NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SANGMIN PARK	09/03/2015
SEUNGHOON RYU	09/03/2015
YOUNGHO KIM	09/03/2015

RECEIVING PARTY DATA

Name:	LG ELECTRONICS INC.	
Street Address:	: 128, YEOUI-DAERO, YEONGDEUNGPO-GU	
City:	SEOUL	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	150-721	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29531657

CORRESPONDENCE DATA

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ROBERT J. GAYBRICK **Correspondent Name:**

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ATTORNEY DOCKET NUMBER: 001082-7419 ROBERT J. GOODELL NAME OF SUBMITTER: SIGNATURE: /Robert J. Goodell/ **DATE SIGNED:** 10/14/2015

Total Attachments: 2

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PATENT REEL: 036789 FRAME: 0125 503522026

Morgan, Lewis & Bocklus (EP U.S. Patent & Trademark Office Substitute Form P10/58/01 (09:2012)

ATTORNEY DOCKET NO.: SOLE/JOINT INVENTION (C.S. Rights Only)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

MOBILE PHONE

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on ______, (Application No. ____); and

WHEREAS, LG ELECTRONICS INC., a corporation of Republic of Korea, whose post office address is 128, Yeoui-daero, Yeongdeungpo-gu, Seoul, 150-721, Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Decia	ration
and Power of Attorney in this application, to insert here in parenthesis (Application No.	, filed
) the filing date and application number of said application when known.	
the fining date and approximation of the fining	

IN TESTIMONY WHEREOF, I/W	E have hereunto set our ha	ınd(s).	
Full Name of First Assignor	Assignor's Signature	be	Date 2015.9.3.
Address c/o Seocho R&D Campus, L 11gil, Seocho-gu, Seoul, Kor	G Electronics Inc. 19, ea	Yangjae-daero	Citizenship Republic of Korea
Full Name of Second Assignor	Assignor's Signature	24	2015/9/3
Address c/o Seocho R&D Campus, L 11gil, Seocho-gu, Seoul, Kor	G Electronics Inc. 19, ea	Yangjae-daero	Citizenship Republic of Korea
Names of additional inventors attached Yes	□No		

PATENT REEL: 036789 FRAME: 0126

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Full Name of Third Assignor Youngho KIM	Assignor's Signature	0分之.	Date 2015 [9] 3
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Names of additional inventors attached Yes	⊠ No		

PATENT REEL: 036789 FRAME: 0127

RECORDED: 10/14/2015